

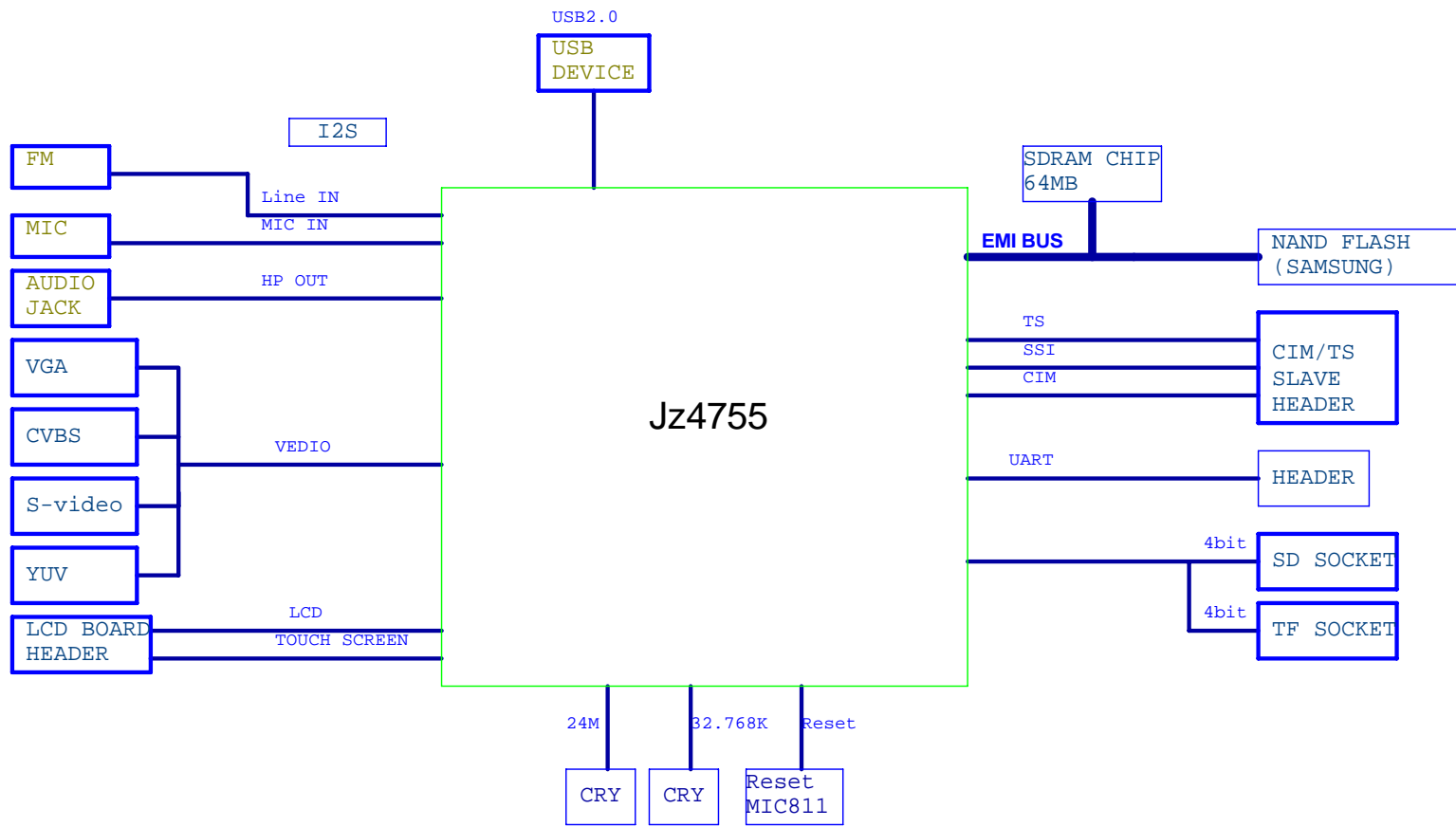


RD4755_Cetus Development Board Schematic Revision 1.3

Title	Page
Cover Sheet	1
System Architecture	2
Jz4755	3
RTC/SDRAM	4
Static Memory/TS/Camera	5
POWER/Boot/Reset	6
SD/USB	7
Audio/FM	8
Video	9
VGA	10
LCD	11
History	12

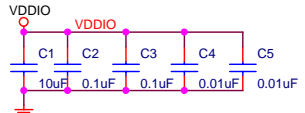
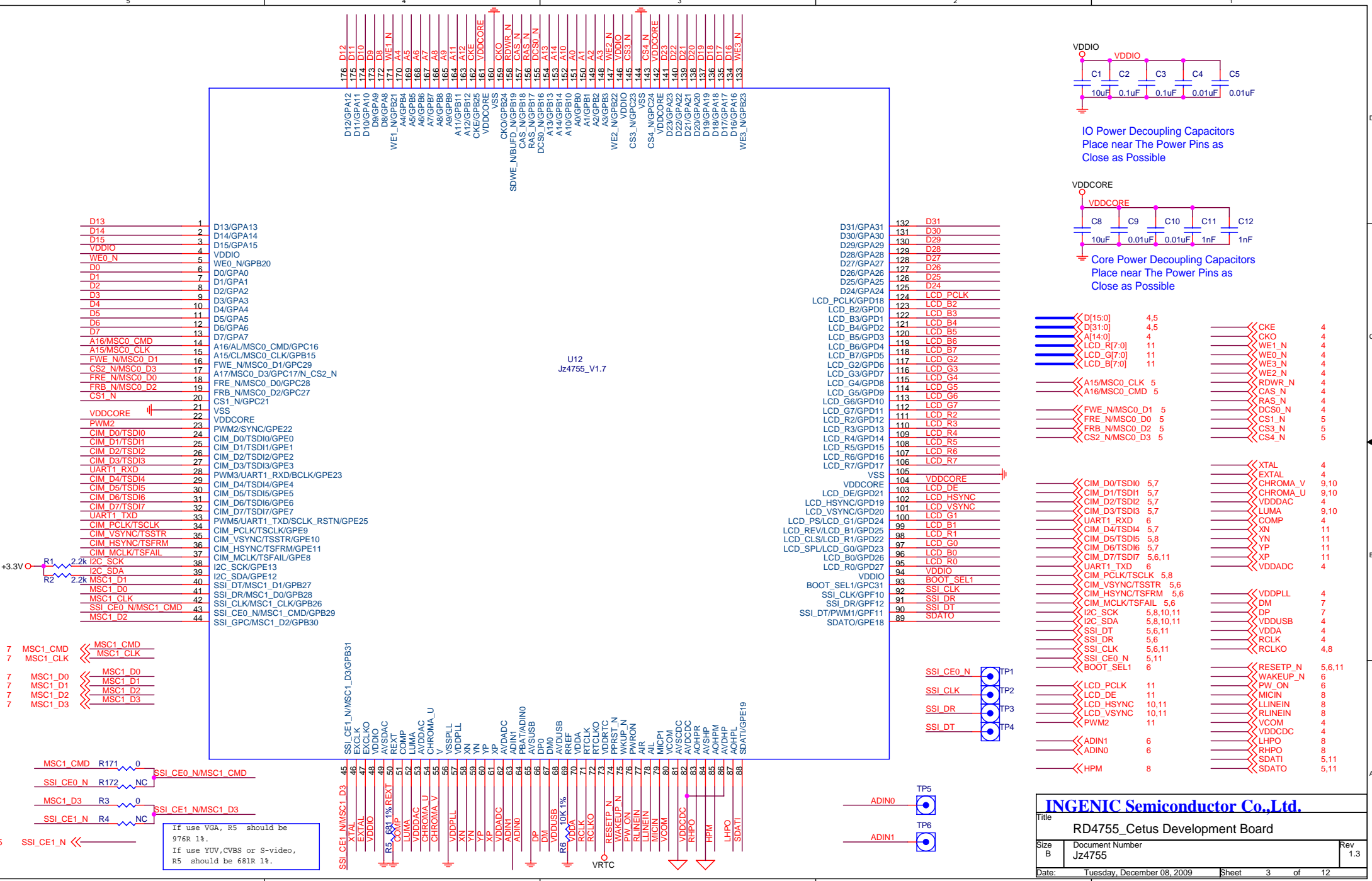
INGENIC Semiconductor Corporation
System Technology Department

INGENIC Semiconductor Co.,Ltd.		
Title	RD4755_Cetus Development Board	
Size	Document Number	Rev
B	Cover	1.3
Date:	Tuesday, December 08, 2009	Sheet 1 of 12

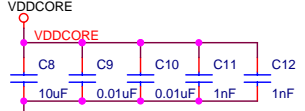


INGENIC Semiconductor Co.,Ltd.

Title		
RD4755_Cetus Development Board		
Size	Document Number	Rev
B	System Architecture	1.3
Date:	Tuesday, December 08, 2009	Sheet 2 of 12



IO Power Decoupling Capacitors
Place near The Power Pins as
Close as Possible



Core Power Decoupling Capacitors
Place near The Power Pins as
Close as Possible

<< D[15:0]	4,5	>> CKE	4
<< D[31:0]	4,5	>> CKO	4
<< A[14:0]	4	>> WE1_N	4
<< LCD_R[7:0]	11	>> WE0_N	4
<< LCD_G[7:0]	11	>> WE3_N	4
<< LCD_B[7:0]	11	>> WE2_N	4
<< A15/MSC0_CLK	5	>> RDWR_N	4
<< A16/MSC0_CMD	5	>> CAS_N	4
<< FW_E_N/MSC0_D1	5	>> RAS_N	4
<< FW_E_N/MSC0_D0	5	>> DCS0_N	4
<< FRB_N/MSC0_D2	5	>> CS1_N	5
<< CS1_N	20	>> CS3_N	5
<< CS2_N/MSC0_D3	5	>> CS4_N	5

<< CIM_D0/TSDI0	5,7	>> XTAL	4
<< CIM_D1/TSDI1	5,7	>> EXTERNAL	4
<< CIM_D2/TSDI2	5,7	>> CHROMA_V	9,10
<< CIM_D3/TSDI3	5,7	>> CHROMA_U	9,10
<< CIM_D4/TSDI4	5,7	>> VDDADC	4
<< CIM_D5/TSDI5	5,8	>> LUMA	9,10
<< CIM_D6/TSDI6	5,8	>> COMP	4
<< CIM_D7/TSDI7	5,6,11	>> XN	11
<< CIM_PCLK/TSCLK	5,8	>> YN	11
<< CIM_VSYNC/TSSTR	5,6	>> YP	11
<< CIM_HSYNC/TSFRM	5,6	>> XP	11
<< CIM_MCLK/TSFAIL	5,6	>> VDDADC	4

<< SSI_CE0_N	6	>> VDDPLL	4
<< SSI_CLK	6	>> DM	7
<< SSI_DR	6	>> DP	7
<< SSI_DT	6	>> VDDUSB	4
<< SSI_CE0_N	5,11	>> VDDA	4
<< BOOT_SEL1	6	>> VDDA	4
<< LCD_PCLK	11	>> RCLK	4
<< LCD_DE	11	>> RCLKO	4,8
<< LCD_HSYNC	10,11	>> RESETP_N	5,6,11
<< LCD_VSYNC	10,11	>> WAKEUP_N	6
<< PWM2	11	>> PW_ON	6
<< ADIN1	6	>> MICIN	8
<< ADIN0	6	>> LINEIN	8
<< HPM	8	>> RLININ	8
<< HPM	8	>> VCOM	4
<< HPM	8	>> VDDCDDC	4
<< HPM	8	>> LHPO	8
<< HPM	8	>> RHPO	8
<< HPM	8	>> SDATI	5,11
<< HPM	8	>> SDATO	5,11

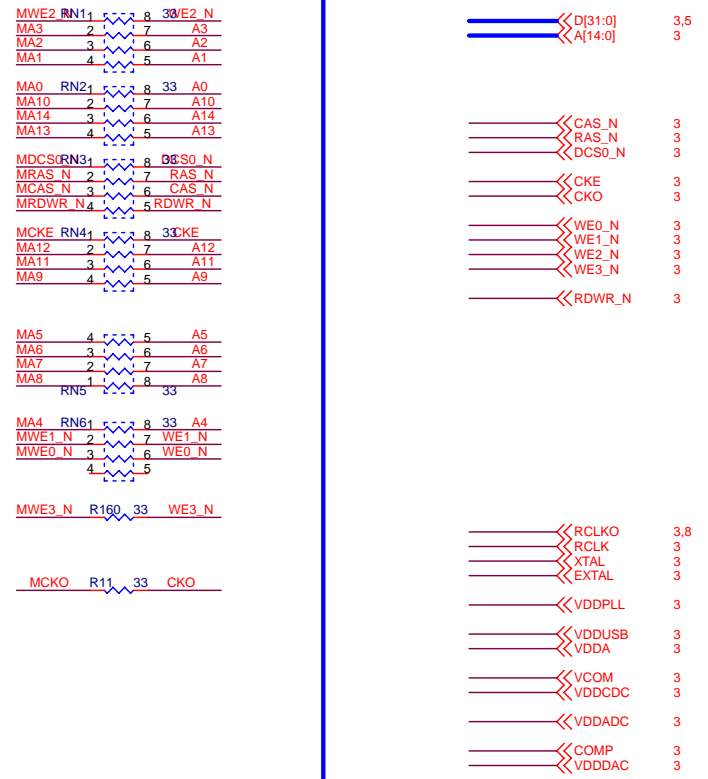
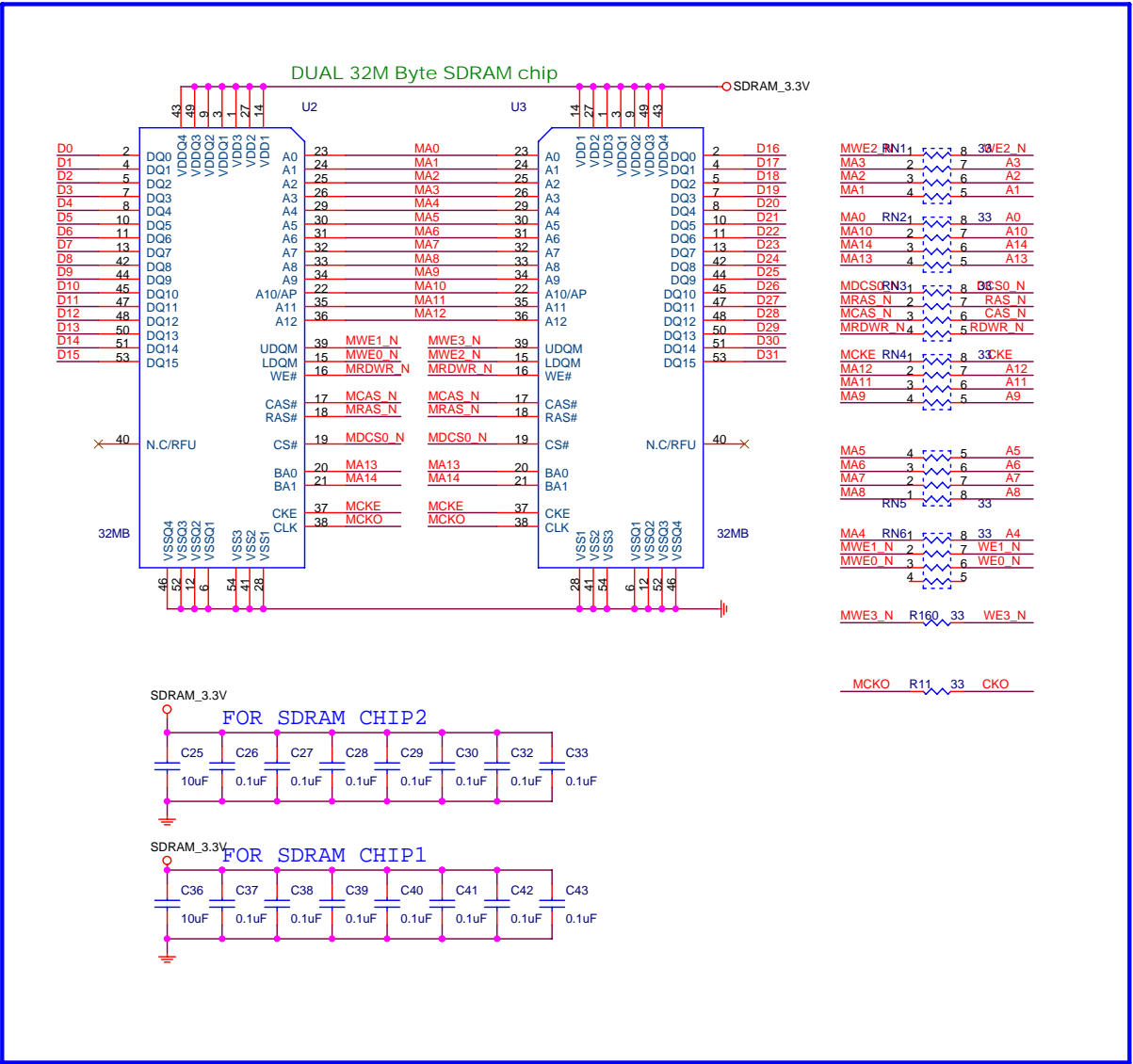
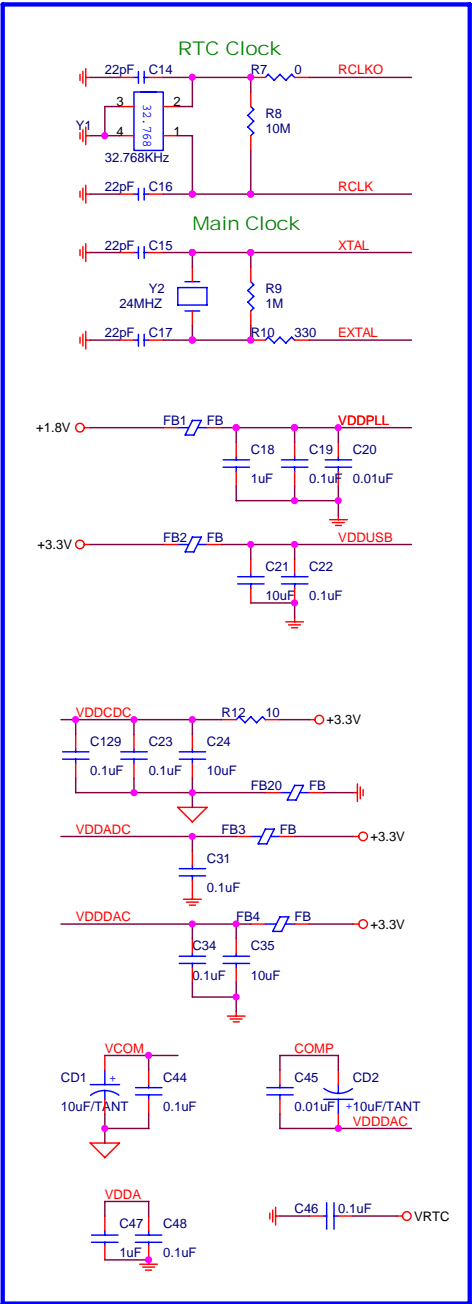
If use VGA, R5 should be 976R 1%.
If use YUV,CVBS or S-video, R5 should be 681R 1%.

INGENIC Semiconductor Co.,Ltd.

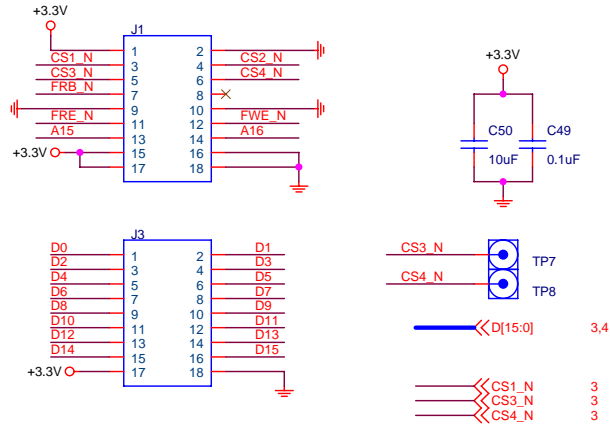
Title: RD4755_Cetus Development Board

Size B Document Number Jz4755 Rev 1.3

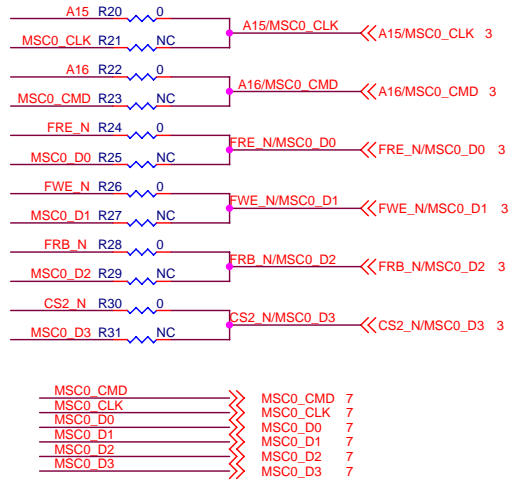
Date: Tuesday, December 08, 2009 Sheet 3 of 12



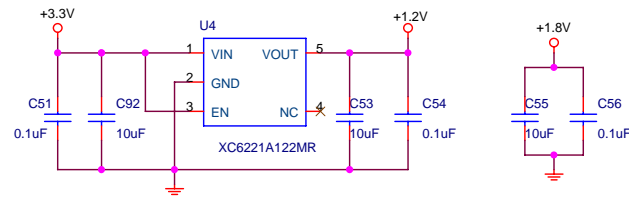
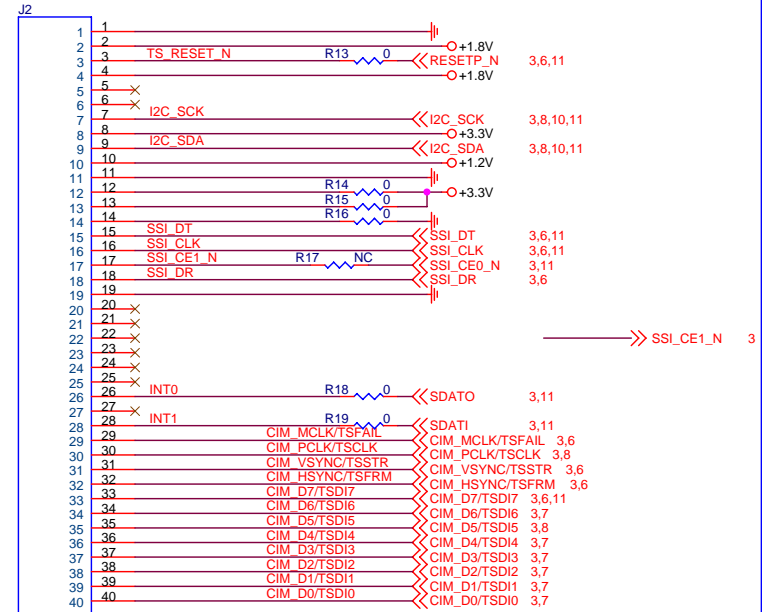
NAND Flash Socket



Note: Nand Flash signals are multiplex with SD:MSC0 signals.

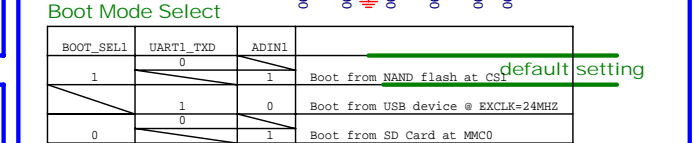
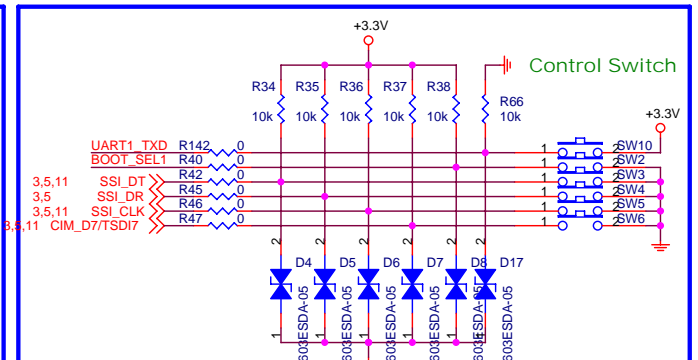
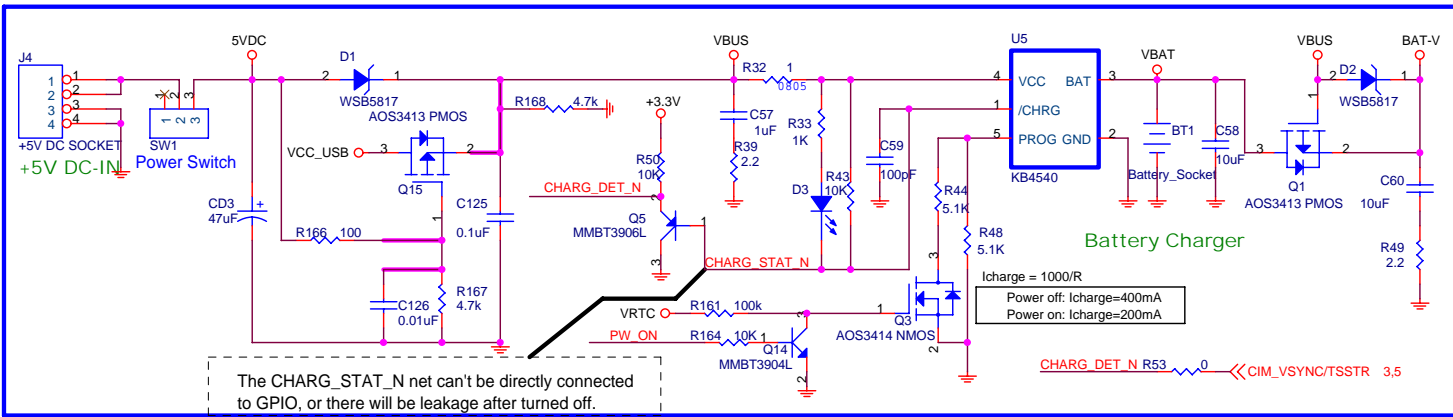


TS/Camera Interface Connector

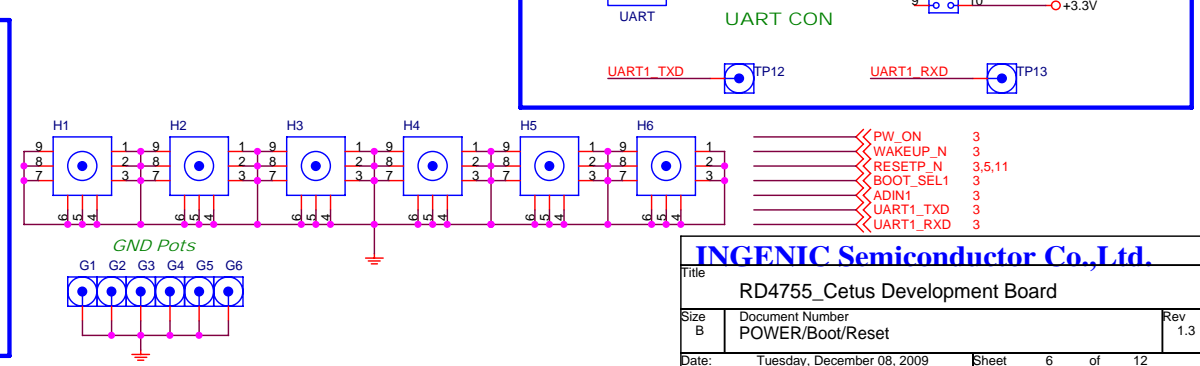
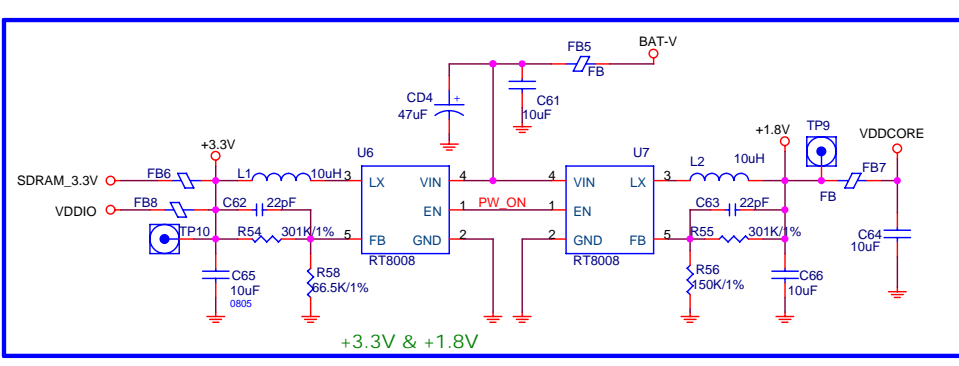
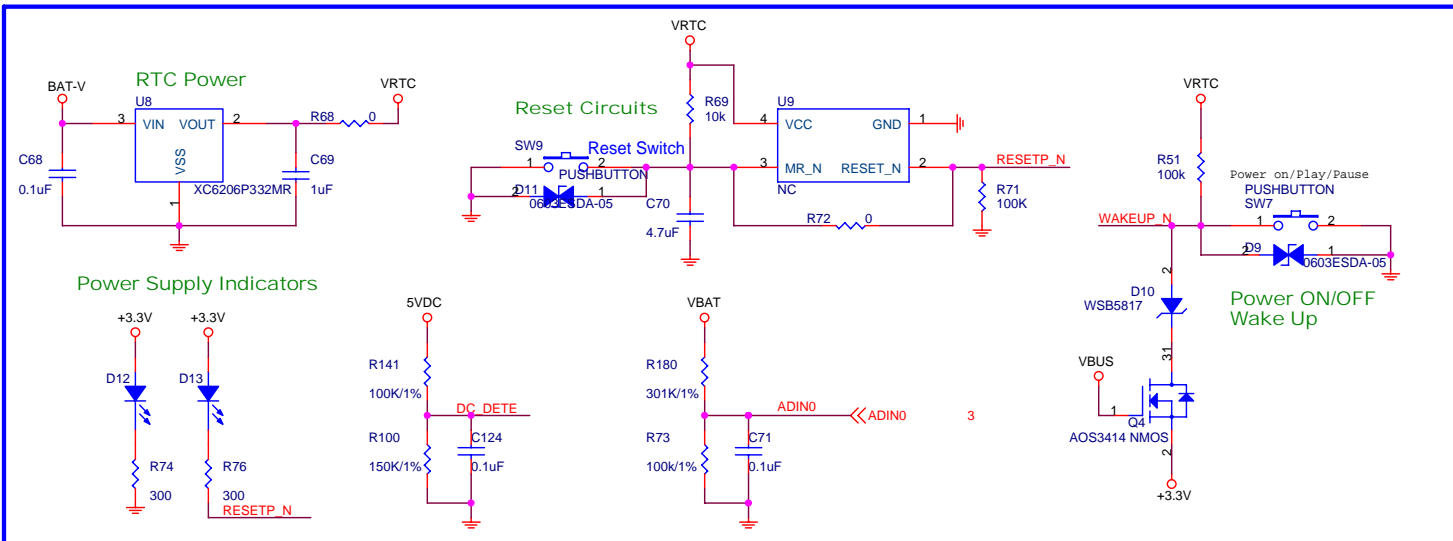
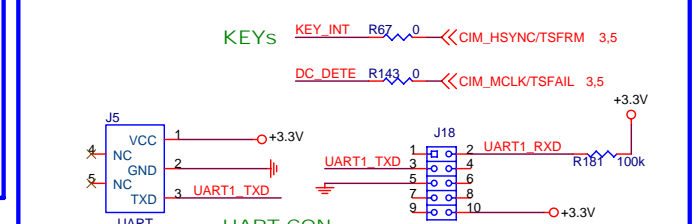
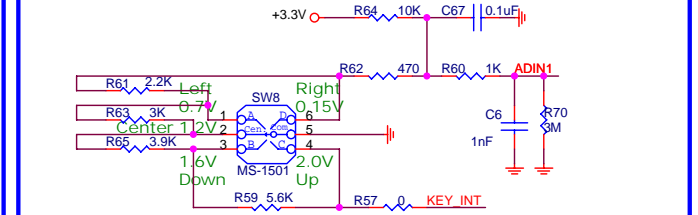


INGENIC Semiconductor Co.,Ltd.

Title		
RD4755_Cetus Development Board		
Size	Document Number	Rev
B	Static Memory/TS/Camera	1.3
Date:	Tuesday, December 08, 2009	Sheet 5 of 12



Note: When boot from USB device, the voltage value of ADIN1 should be > 0V and <= 0.3V.



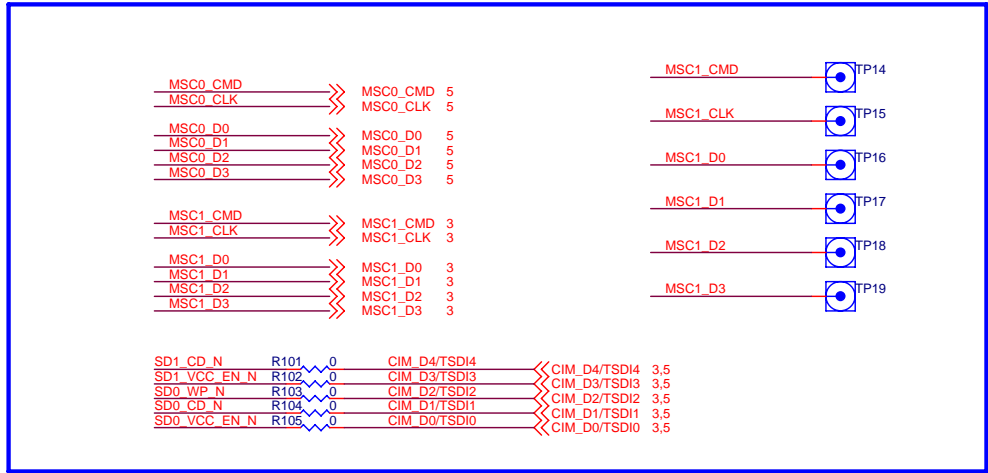
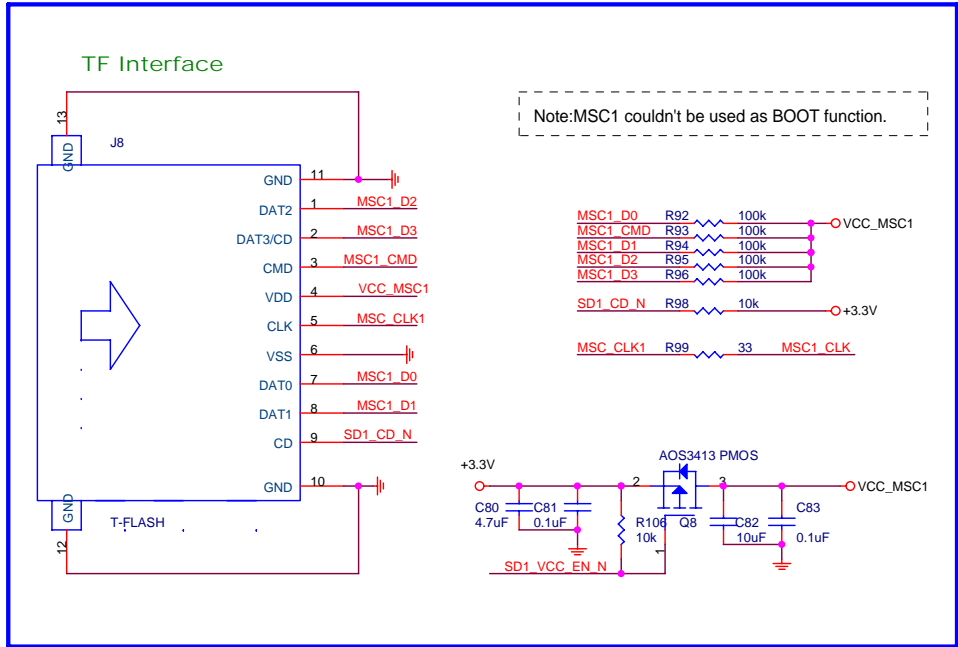
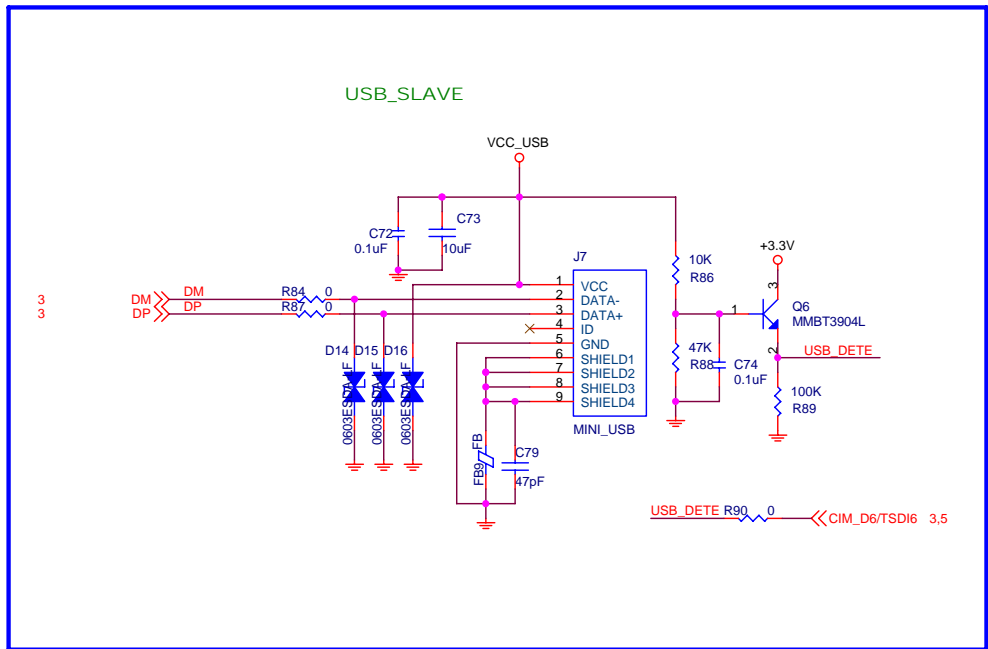
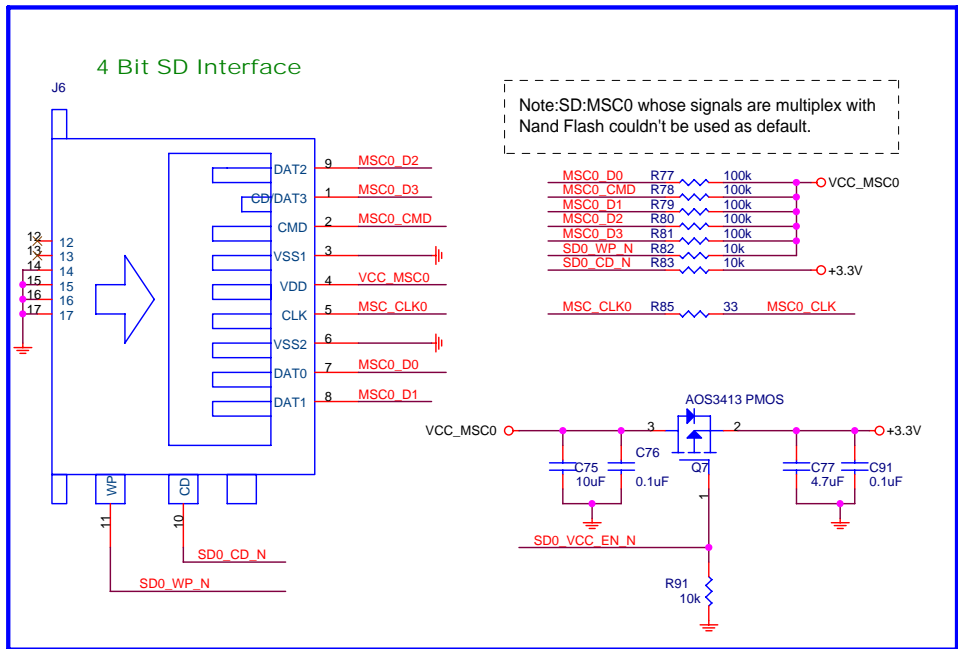
INGENIC Semiconductor Co., Ltd.

Title: RD4755_Cetus Development Board

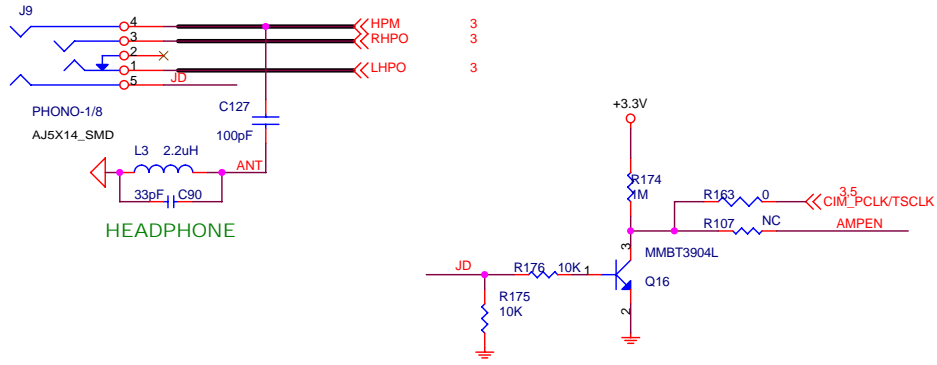
Size: Document Number
 B POWER/Boot/Reset

Date: Tuesday, December 08, 2009 Sheet 6 of 12

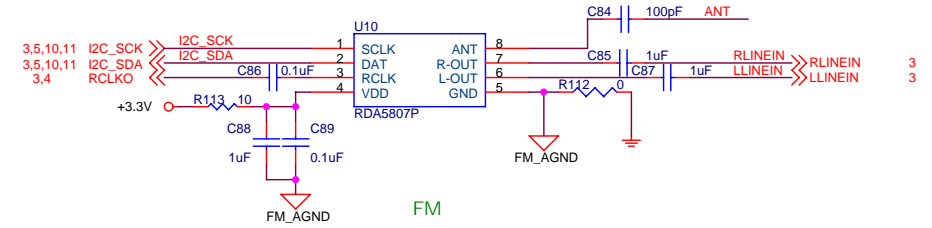
Rev: 1.3



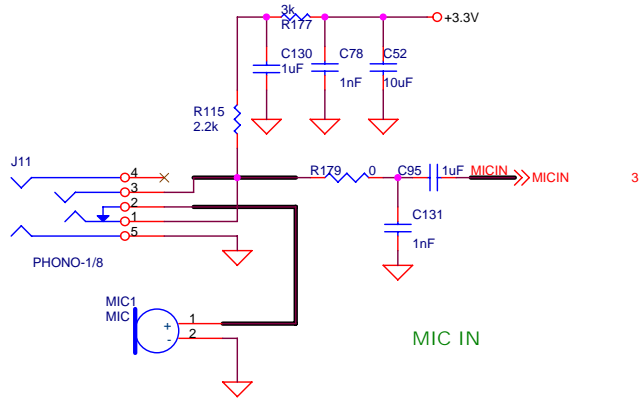
The trace between the HPM pin and the headphone jack must be as short as possible.



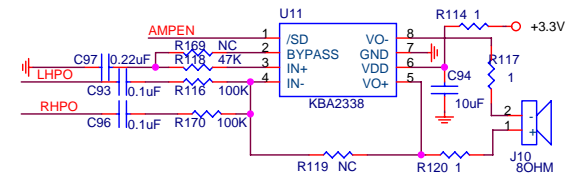
HEADPHONE



FM

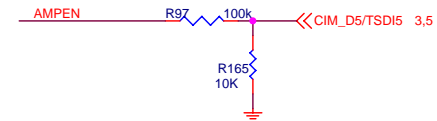


MIC IN



Speaker Out Connector

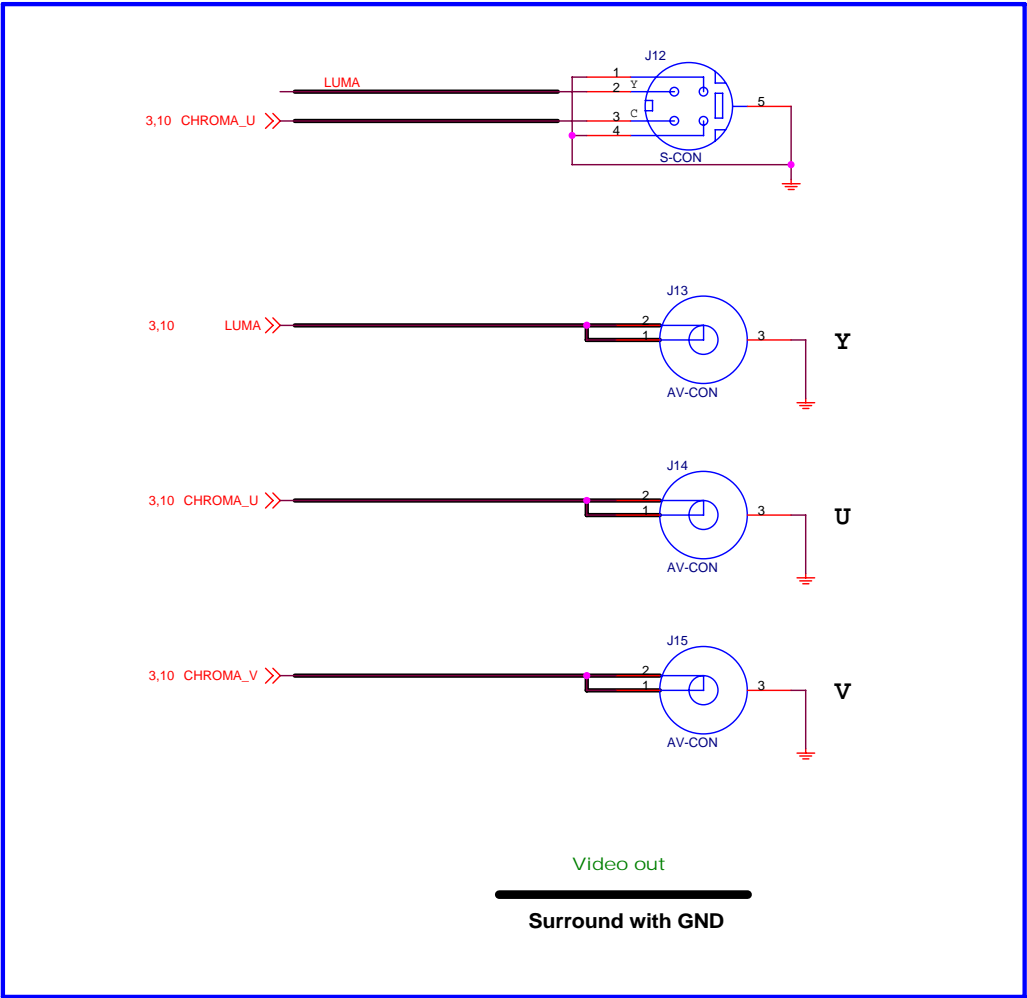
If U11 is LM4890, R169=0R, R118=0, C97=0.1uF, R119=20K.



Surround with GND

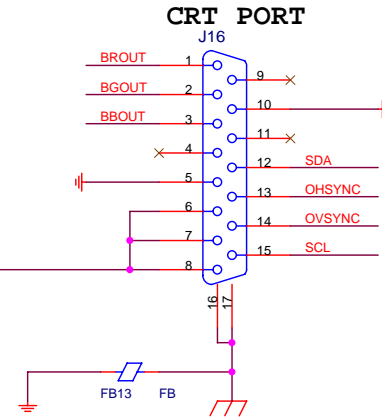
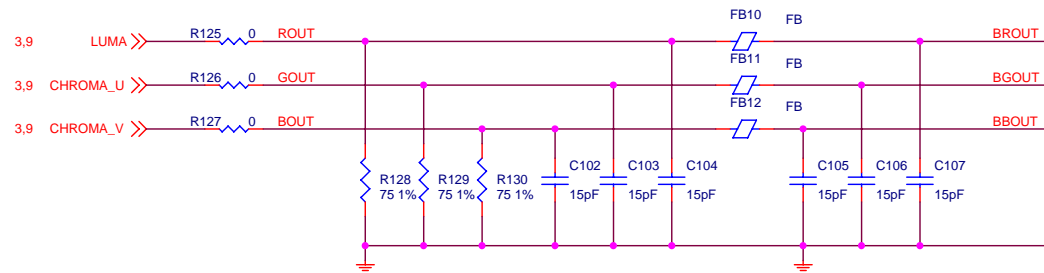
INGENIC Semiconductor Co.,Ltd.

Title	RD4755_Cetus Development Board	
Size	Document Number	Rev
B	Audio/FM	1.3
Date:	Tuesday, December 08, 2009	Sheet 8 of 12

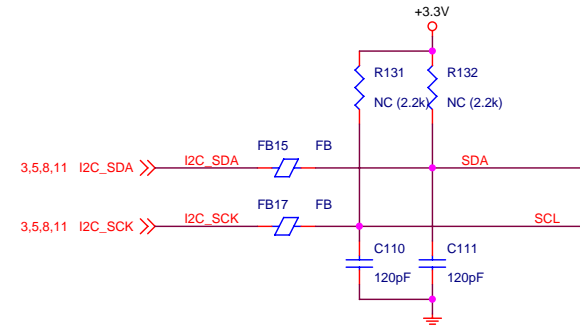
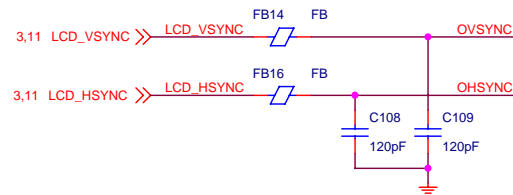
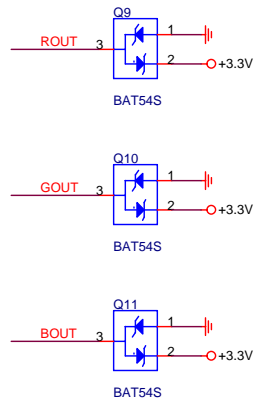


INGENIC Semiconductor Co.,Ltd.

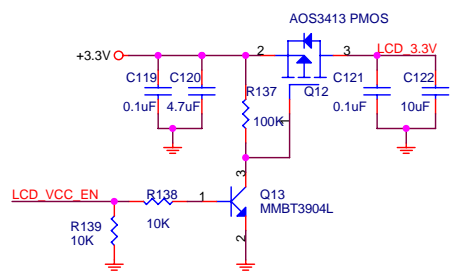
Title		RD4755_Cetus Development Board	
Size	Document Number	Rev	
B		1.3	
Date:	Tuesday, December 08, 2009	Sheet	9 of 12



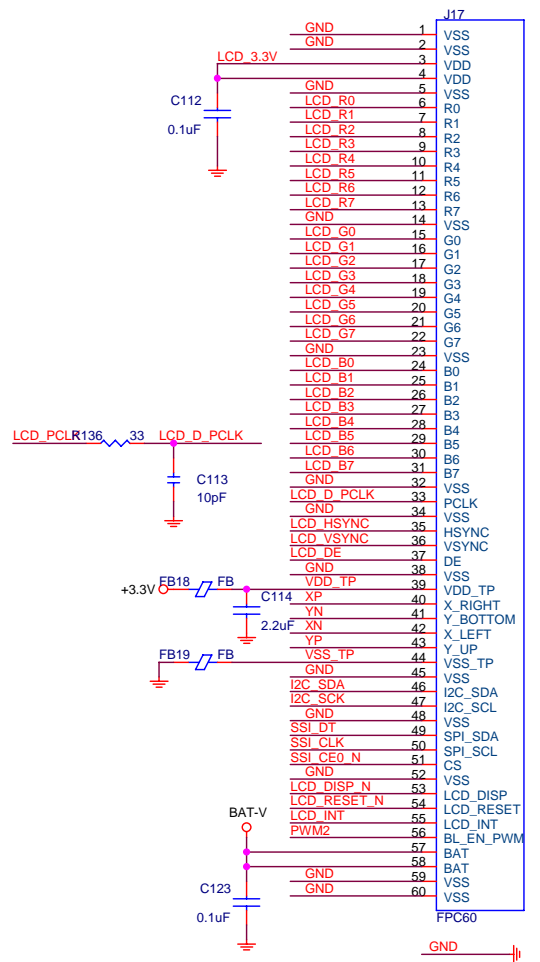
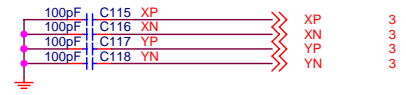
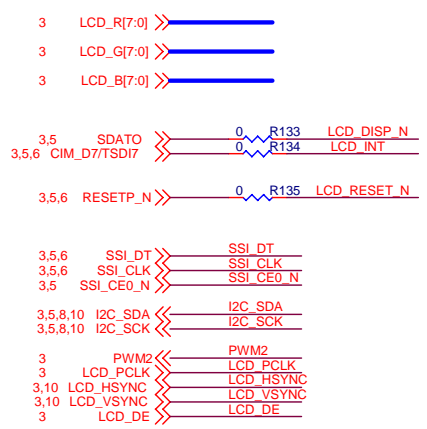
ESD PROTECTION



INGENIC Semiconductor Co.,Ltd.		
Title RD4755_Cetus Development Board		
Size B	Document Number VGA	Rev 1.3
Date:	Tuesday, December 08, 2009	Sheet 10 of 12



LCD Power Control LCD_VCC_EN R140 0 << SDATI 3,5



LCD Connector

Data Revision Change

Mar. 09. 2009	Rev1.0	1. First Revision
Apr. 15. 2009	Rev1.1	<ol style="list-style-type: none"> 1. PAGE06: Delete R41,Q2,R52. 2. PAGE06 :Change the Icharge control circuit. 3. PAGE06: Change the BAT detect circuit. 4. PAGE06: Change the control circuit of power supply. 5. PAGE07: Change C73 from 10uF to NC, in order to avoid a BAT-V negative pulse when USB device pull out. 6. PAGE08: Change CD5,CD6 to 220uF. 7. PAGE08: Add R163 for JACK_DETE and add R165 for AMPEN. 8. PAGE08: Change the amplifier enable net's name from "AMPEN_N" to "AMPEN" 9. PAGE09: Delete R121-R124 and C98-C101 for video out balance. 10. PAGE08: Add R169 for reserve. 11. PAGE03: Exchange LHPO's and RHPO's PIN numbers in Jz4755 source package. 12. PAGE03: Exchange AIL's and AIR's PIN numbers in Jz4755 source package. 13. PAGE08: Delete R108-R111. 14. PAGE08: Add FB20,FB21 for EMI. 15. PAGE08: Add R170.
Apr. 27. 2009	Rev1.2	<ol style="list-style-type: none"> 1. PAGE03: Change the audio pins' number in Jz4755 source package. 2. PAGE03: ADD R171 and R172 to select SSI_CE0_N or MSC1_CMD. 3. PAGE06: Change the net of R47.1 from SSI_CE0_N to CIM_D7/TSDI7. 4. PAGE08: Change HPOUT circuit.
May. 04. 2009	Rev1.2.1	1. PAGE04: ADD R173 for AGND partition.
Aug. 14. 2009	Rev1.3	<ol style="list-style-type: none"> 1. PAGE03: Change the Jz4755 decouple capacitors. 2. PAGE04: Add C129 for VDDCDC's decouple. 3. PAGE06: Change BAT detect circuit for protecting ADIN0. 4. PAGE06: ADD R181 for UART1_RXD. 5. PAGE08: Change the JACK_DETE circuit. 6. PAGE08: Change the MIC IN circuit. 7. PAGE08: Change R173 to FB20. 8. PAGE08: Change R97 to 100k. 9. PAGE08: Change R174 to 1M.

INGENIC Semiconductor Co.,Ltd.		
Title		
RD4755_Cetus Development Board		
Size	Document Number	Rev
B	History	1.3
Date:	Tuesday, December 08, 2009	Sheet 12 of 12